









**Cross Category**

 <u>AN257</u>	THERMAL CHARACTERISTICS OF THE MULTIWATT PACKAGE
 <u>AN258</u>	THERMAL CHARACTERISTICS OF THE PENTAWATT/HEPTAWATT PACKAGES
 <u>AN260</u>	HANDLING AND MOUNTING ICS IN PLASTIC POWER PACKAGES
 <u>AN261</u>	DESIGNING WITH THERMAL IMPEDANCE
 <u>AN262</u>	THERMAL MANAGEMENT IN SOURCE MOUNTING
 <u>AN264</u>	RESISTANCE TO SOLDERING HEAT AND THERMAL CHARACTERISTICS OF SMDS
 <u>AN628</u>	DESIGNING A HIGH POWER FACTOR SWITCHING PREREGULATOR WITH THE L4981 CONTINUOUS MODE
 <u>AN668</u>	A NEW HIGH POWER IC SURFACE MOUNT PACKAGE; POWER SO-20 POWER IC PACKAGING FROM INSERTION TO SURFACE MOUNTING